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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	10000
Number of Logic Elements/Cells	40000
Total RAM Bits	4075520
Number of I/O	604
Number of Gates	-
Voltage - Supply	0.95V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	1152-BBGA, FCBGA
Supplier Device Package	1152-FCBGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfscm3ga40ep1-5ff1152c

DLLs and dynamic glitch free clock MUXs which are required in today's high end system designs. High-speed, high-bandwidth I/O make this family ideal for high-throughput systems.

The ispLEVER® design tool from Lattice allows large complex designs to be efficiently implemented using the LatticeSC family of FPGA devices. Synthesis library support for LatticeSC is available for popular logic synthesis tools. The ispLEVER tool uses the synthesis tool output along with the constraints from its floor planning tools to place and route the design in the LatticeSC device. The ispLEVER tool extracts the timing from the routing and back-annotates it into the design for timing verification.

Lattice provides many pre-designed IP (Intellectual Property) ispLeverCORE™ modules for the LatticeSC family. By using these IPs as standardized blocks, designers are free to concentrate on the unique aspects of their design, increasing their productivity.

Innovative high-performance FPGA architecture, high-speed SERDES with PCS support, sysMEM embedded memory and high performance I/O are combined in the LatticeSC to provide excellent performance for today's leading edge systems designs. Table 1-3 details the performance of several common functions implemented within the LatticeSC.

Table1-3. Speed Performance for Typical Functions[1]

Functions	Performance (MHz)[2]
32-bit Address Decoder	539
64-bit Address Decoder	517
32:1 Multiplexer	779
64-bit Adder (ripple)	353
32x8 Distributed Single Port (SP) RAM	768
64-bit Counter (up or down counter, non-loadable)	369
True Dual-Port 1024x18 bits	372
FIFO Port A: x36 bits, B: x9 bits	375

1. For additional information, see Typical Building BLock Function Performance table in this data sheet.
2. Advance information (-7 speed grade).

PURESPEED I/O Buffer Banks

LatticeSC devices have seven PURESPEED I/O buffer banks; each is capable of supporting multiple I/O standards. Each PURESPEED I/O bank has its own I/O supply voltage (V_{CCIO}), and two voltage references V_{REF1} and V_{REF2} resources allowing each bank to be completely independent from each other. Figure 2-26 shows the seven banks and their associated supplies. Table 2-7 lists the maximum number of I/Os per bank for the whole LatticeSC family.

In the LatticeSC devices, single-ended output buffers and ratioed input buffers (LVTTL, LVCMOS, PCI33 and PCIX33) are powered using V_{CCIO}. In addition to the bank V_{CCIO} supplies, the LatticeSC devices have a V_{CC} core logic power supply, and a V_{CCAUX} supply that power all differential and referenced buffers. VCCAUX also powers a predriver of single-ended output buffers to enhance buffer performance.

Each bank can support up to two separate VREF voltages, VREF1 and VREF2 that set the threshold for the referenced input buffers. In the LatticeSC devices any I/O pin in a bank can be configured to be a dedicated reference voltage supply pin. Each I/O is individually configurable based on the bank's supply and reference voltages.

Differential drivers have user selectable internal or external bias. External bias is brought in by the VREF1 pin in the bank. External bias for differential buffers is needed for applications that requires tighter than standard output common mode range.

Since a bank can have only one external bias circuit for differential drivers, LVDS and RSDS differential outputs can be mixed in a bank.

If a differential driver is configured in a bank, one pin in that bank becomes a DIFFR pin. This DIFFR pin must be connected to ground via an external 1K +/-1% ohm resistor. Note that differential drivers are not supported in banks 1, 4 and 5.

In addition, there are dedicated Terminating Supply (V_{TT}) pins to be used as terminating voltage for one of the two ways to perform parallel terminations. These V_{TT} pins are available in banks 2-7, these pins are not available in some packages. When VTT termination is not required, or used to provide the common mode termination voltage (VCMT), these pins can be left unconnected on the device. If the internal or external VCMT function for differential input termination is used, the VTT pins should be unconnected and allowed to float.

There are further restrictions on the use of V_{TT} pins, for additional details refer to technical information at the end of this data sheet.

Switching Characteristics

All devices are 100% functionally tested. Listed below are representative values of internal and external timing parameters. For more specific, more precise, and worst-case guaranteed data at a particular temperature and voltage, use the values reported by the static timing analyzer in the ispLEVER design tool from Lattice and back-annotate to the simulation net list.

LatticeSC/M Internal Timing Parameters[1]

Over Recommended Commercial Operating Conditions at VCC = 1.2V +/- 5%

Parameter	Symbol	Description	-7		-6		-5		Units
			Min.	Max.	Min.	Max.	Min.	Max.	
PFU Logic Mode Timing									
t_{LUT4_PFU}	CTOF_DEL	LUT4 delay (A to D inputs to F output)	—	0.045	—	0.050	—	0.054	ns
t_{LUT5_PFU}	MTOOFX_DEL	LUT5 delay (inputs to output)	—	0.152	—	0.172	—	0.192	ns
t_{LSR_PFU}	LSR_DEL	Set/Reset to output (asynchronous)	—	0.378	—	0.426	—	0.474	ns
t_{SUM_PFU}	M_SET	Clock to Mux (M0,M1) input setup time	0.113	—	0.131	—	0.148	—	ns
t_{HM_PFU}	M_HLD	Clock to Mux (M0,M1) input hold time	-0.041	—	-0.046	—	-0.052	—	ns
t_{SUD_PFU}	DIN_SET	Clock to D input setup time	0.072	—	0.083	—	0.094	—	ns
t_{HD_PFU}	DIN_HLD	Clock to D input hold time	-0.028	—	-0.032	—	-0.035	—	ns
t_{CK2Q_PFU}	REG_DEL	Clock to Q delay, D-type register configuration	—	0.224	—	0.252	—	0.279	ns
t_{LE2Q_PFU}	LTCH_DEL	Clock to Q delay latch configuration	—	0.294	—	0.331	—	0.367	ns
t_{LD2Q_PFU}	TLTCH_DEL	D to Q throughput delay when latch is enabled	—	0.300	—	0.338	—	0.376	ns
PFU Memory Mode Timing									
t_{CORAM_PFU}	CLKTOF_DEL	Clock to Output	—	0.575	—	0.649	—	0.724	ns
t_{SUDATA_PFU}	DIN_SET	Data Setup Time	-0.024	—	-0.026	—	-0.027	—	ns
t_{HDATA_PFU}	DIN_HLD	Data Hold Time	0.075	—	0.084	—	0.094	—	ns
t_{SUADDR_PFU}	WAD_SET	Address Setup Time	-0.176	—	-0.196	—	-0.215	—	ns
t_{HADDR_PFU}	WAD_HLD	Address Hold Time	0.110	—	0.124	—	0.138	—	ns
t_{SUWREN_PFU}	WE_SET	Write/Read Enable Setup Time	0.014	—	0.019	—	0.024	—	ns
t_{HWREN_PFU}	WE_HLD	Write/Read Enable Hold Time	0.078	—	0.086	—	0.094	—	ns
PIC Timing									
PIO Input/Output Buffer Timing									
t_{IN_PIO}	IN_DEL	Input Buffer Delay(LVCMOS25)	—	0.578	—	0.661	—	0.744	ns
t_{OUT_PIO}	DOPADI_DEL	Output Buffer Delay(LVCMOS25)	—	2.712	—	3.027	—	3.395	ns
t_{SUI_PIO}	DIN_SET	Input Register Setup Time (Data Before Clock)	0.277	—	0.312	—	0.348	—	ns
t_{HI_PIO}	DIN_HLD	Input Register Hold Time (Data after Clock)	-0.267	—	-0.306	—	-0.345	—	ns
t_{COO_PIO}	CK_DEL	Output Register Clock to Output Delay	—	0.513	—	0.571	—	0.639	ns
t_{SUCE_PIO}	CE_SET	Input Register Clock Enable Setup Time	—	0.000	—	0.000	—	0.000	ns
t_{HCE_PIO}	CE_HLD	Input Register Clock Enable Hold Time	—	0.129	—	0.145	—	0.161	ns
t_{SULSR_PIO}	LSR_SET	Set/Reset Setup Time	0.057	—	0.060	—	0.063	—	ns
t_{HLSR_PIO}	LSR_HLD	Set/Reset Hold Time	-0.151	—	-0.159	—	-0.169	—	ns
t_{LE2Q_PIO}	CK_DEL	Input Register Clock to Q delay latch configuration	—	0.335	—	0.372	—	0.410	ns
t_{LD2Q_PIO}	DIN_DEL	Input Register D to Q throughput delay when latch is enabled	—	0.578	—	0.647	—	0.717	ns

Figure 3-12. Waveforms First Read after Full Flag

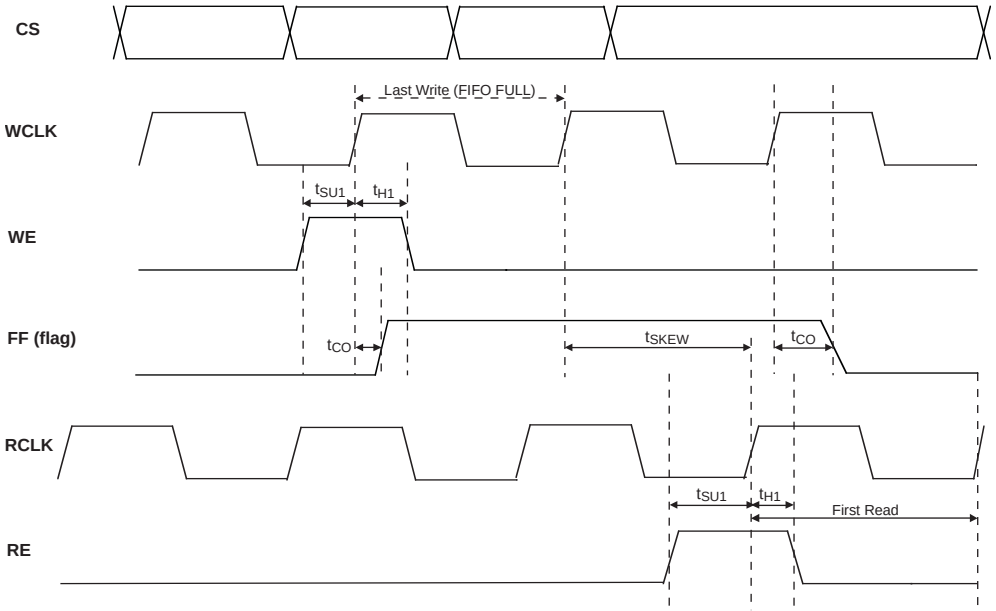
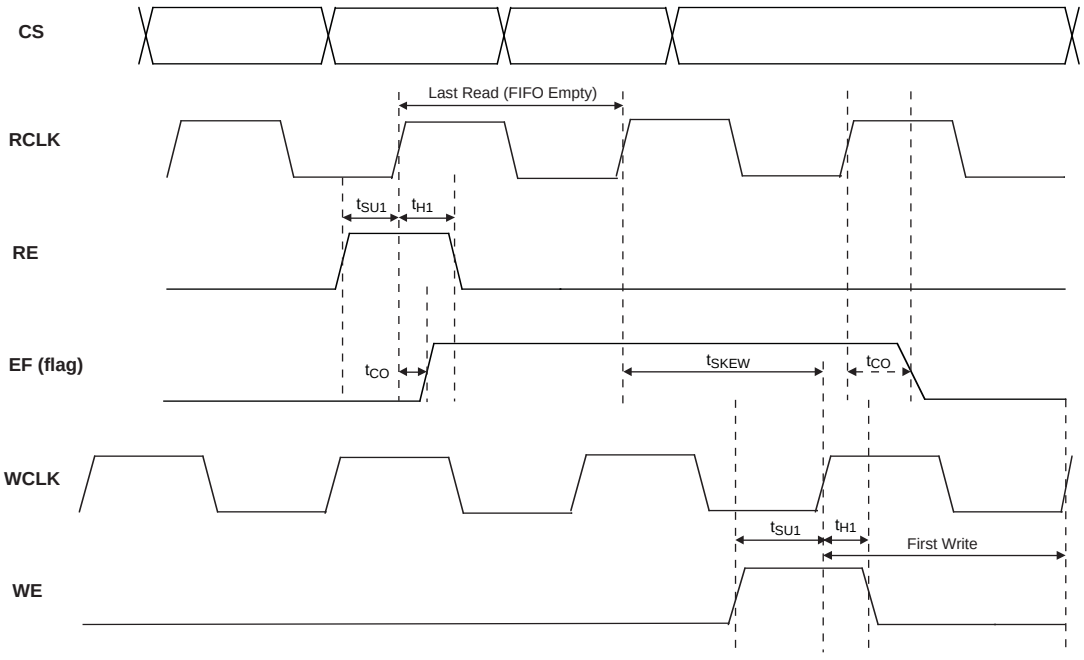


Figure 3-13. Waveform First Write after Empty Flag



Signal Descriptions (Cont.)

Signal Name	I/O	Description
RESETN		Reset. (Also sent to general routing). During configuration it resets the configuration state machine. After configuration this pin can perform the global set/reset (GSR) functions or can be used as a general input pin.
CFGIRQN	O	MPI Interrupt request active low signal is controlled by system bus interrupt controller and may be sourced from any bus error or MPI configuration error. It can be connected to one of MPC860 IRQ pins.
TSALLN	I	Tristates all I/O.
Configuration Pads (User I/O if not used. Used during sysCONFIG.)		
HDC/SI	O	High During Configuration is output high until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this pin is used to download the read command and initial read address into the Flash memory device on the falling edge of SCK. This pin will be connected to SI of the memory. If the SPI mode is used, the 8-bit instruction code 0x03 will be downloaded followed by a 24-bit starting address of 0x000000 or a non-zero stat address for partial reconfiguration. If the SPIX mode has been selected, the 8-bit instruction captured on D[7:0] at power-up will be shifted in and followed by a 32-bit starting address of 0x000000.
LDCN/SCS	O	Low During Configuration is output low until configuration is complete. It is used as a control output, indicating that configuration is not complete. For SPI modes, this is an active low chip select for Flash memories. It will go active after INITN goes high but before SCK begins. During power up LDCN will be low. Once INITN goes high, LDCN will go high for 100ns-200ns after which time it will go back low and configuration can begin. During the 100ns-200ns period, the read instruction will be latched for SPIX mode.
DOUT	O	Serial data output that can drive the D0/DIN of daisy-chained slave devices. The data-stream from this output will propagate preamble bits of the bitstream to daisy-chained devices. Data out on DOUT changes on the rising edge of CCLK.
QOUT/CEON	O	During daisy-chaining configuration, QOUT is the serial data output that can drive the D0/DIN of daisy-chained slave devices that do not propagate preamble bits. Data out on QOUT changes on the rising edge of CCLK. During parallel-chaining configuration, active low CEON enables the cascaded slave device to receive bitstream data.
RDN	I	Used in the asynchronous peripheral configuration mode. A low on RDN changes D[7:3] into status outputs. WRN and RDN should not be used simultaneously. If they are, the write strobe overrides.
WRN	I	When the FPGA is selected, a low on the write strobe, WRN, loads the data on D[7:0] inputs into an internal data buffer.
CS0N CS1	I	Used in the asynchronous peripheral, slave parallel and MPI modes. The FPGA is selected when CS0N is low and CS1 is high. During configuration, a pull-up is enabled on both except with MPI DMA access control.
A[21:0]	I/O	In master parallel mode, A[21:0] is an output and will address the configuration EPROMs up to 4 MB space. For MPI configuration mode, A[17:0] will be the MPI address MPI_ADDR[31:14], A[19:18] will be the transfer size and A[21:20] will be the burst mode and burst in process.

Signal Descriptions (Cont.)

Signal Name	I/O	Description
MPI_STRBN	I	Driven active low indicates the start of a transaction on the PowerPC bus. MPI will strobe the address bus at next rising edge of clock.
MPI_ADDR[31:14]	I	Address bus driven by a PowerPC bus master. Only 18-bit width is needed. It has to be the least significant bit of the PowerPC 32-bit address A[31:14].
MPI_DAT[n:0]	I/O	Selectable data bus width from 8, and 16-bit. Driven by a bus master in a write transaction. Driven by MPI in a read transaction.
MPI_PAR[m:0]	I/O	Selectable parity bus width from 1, 2, and 3-bit. MPI_DP[0] for MPI_D[7:0], MPI_DP[1] for MPI_D[15:8] and MPI_DP[2] for MPI_D[23:16].
MPI_TA	O	Transfer acknowledge. Driven active low indicates that MPI received the data on the write cycle or returned data on the read cycle.
MPI_TEA	O	Transfer Error Acknowledge. Driven active low indicates that MPI detects a bus error on the internal system bus for current transaction.
MPI_RETRY	O	Active low MPI Retry requests the MPC860 to relinquish the bus and retry the cycle.
Multi-chip Alignment (User I/O if not used.)		
MCA_DONE_OUT	O	Multi-chip alignment done output (to second MCA chip)
MCA_DONE_IN	I	Multi-chip alignment done input (from second MCA chip)
MCA_CLK_P[1:2]_OUT	O	Multi-chip alignment clock [1:2] output (sourced by MCA master chip)
MCA_CLK_P[1:2]_IN	I	Multi-chip alignment clock [1:2] input (from MCA master chip
TEMP	—	Temperature sensing diode pin. Dedicated pin. Accuracy is typically +/- 10°C.
Miscellaneous Dedicated Pins		
XRES	—	External reference resistor between this pin and ground. The reference resistor is used to calibrate the programmable terminating resistors used in the I/Os. Dedicated pin. Value: 1K ± 1% ohm.
DIFFRx	—	Only used if a differential driver is used in a bank. This DIFFRx must be connected to ground via an external 1K ±1% ohm resistor for all banks that have a differential driver.
SERDES Block (Dedicated Pins)		
[A:D]_HDINPx_[L/R]	I	High-speed input (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDINNx_[L/R]	I	High-speed input (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTPx_[L/R]	O	High-speed output (positive) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_HDOUTNx_[L/R]	O	High-speed output (negative) channel x on left [L] or right [R] side of device. PCS quad is defined in the dual function name column of the Logic Signal Connection table.
[A:D]_REFCLKP_[L/R]	I	Ref clock input (positive), aux channel on left [L] or right [R] side of device.
[A:D]_REFCLKN_[L/R]	I	Ref clock input (negative), aux channel on left [L] or right [R] side of device.

LFSC/M15 Logic Signal Connections: 256 fpBGA[1,2]

Ball Number	LFSC/M15		
	Ball Function	VCCIO Bank	Dual Function
E4	A_VDDAX25_L	-	
B1	A_REFCLKP_L	-	
C1	A_REFCLKN_L	-	
D2	RESP_ULC	-	
F5	RESETN	1	
D1	DONE	1	
E1	INITN	1	
E2	M0	1	
E3	M1	1	
E5	M2	1	
E6	M3	1	
F2	PL15A	7	ULC_PLLT_IN_A/ULC_PLLT_FB_B
F1	PL15B	7	ULC_PLLC_IN_A/ULC_PLLC_FB_B
F3	PL17A	7	ULC_DLLT_IN_C/ULC_DLLT_FB_D
G1	PL17B	7	ULC_DLLC_IN_C/ULC_DLLC_FB_D
G4	PL18D	7	VREF2_7
H3	PL22A	7	
H2	PL22B	7	
H5	PL22C	7	VREF1_7
G5	PL22D	7	DIFFR_7
H1	PL23A	7	PCLKT7_1
J1	PL23B	7	PCLKC7_1
J2	PL24A	7	PCLKT7_0
J3	PL24B	7	PCLKC7_0
H4	PL24C	7	PCLKT7_2
H6	PL24D	7	PCLKC7_2
J4	PL26A	6	PCLKT6_0
K5	PL26B	6	PCLKC6_0
J5	PL26C	6	PCLKT6_1
J6	PL26D	6	PCLKC6_1
K1	PL28A	6	
L1	PL28B	6	
L4	PL28C	6	PCLKT6_2
K4	PL28D	6	PCLKC6_2
L2	PL31C	6	VREF1_6
L3	PL35A	6	
M3	PL35B	6	
M2	PL35D	6	DIFFR_6
M1	PL37A	6	
N1	PL37B	6	
P2	PL41D	6	VREF2_6
M5	PL43A	6	

LFSC/M40, LFSC/M80 Logic Signal Connections: 1152 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M40			LFSC/M80		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
C32	VCC12	-		VCC12	-	
E34	NC	-		PL22A	7	
F34	NC	-		PL22B	7	
F33	NC	-		PL24A	7	
G33	NC	-		PL24B	7	
K30	NC	-		PL25A	7	
L30	NC	-		PL25B	7	
G34	NC	-		PL26A	7	
H34	NC	-		PL26B	7	
M32	NC	-		PL39A	7	
N32	NC	-		PL39B	7	
P28	NC	-		PL39C	7	
R28	NC	-		PL39D	7	
J34	NC	-		PL41A	7	
K34	NC	-		PL41B	7	
P30	NC	-		PL41C	7	
R30	NC	-		PL41D	7	
W34	NC	-		PL59A	6	
Y34	NC	-		PL59B	6	
W32	NC	-		PL61A	6	
Y32	NC	-		PL61B	6	
AA34	NC	-		PL64A	6	
AB34	NC	-		PL64B	6	
AC34	NC	-		PL67A	6	
AD34	NC	-		PL67B	6	
Y30	NC	-		PL68A	6	
AA30	NC	-		PL68B	6	
AB33	NC	-		PL69A	6	
AC33	NC	-		PL69B	6	
AC2	NC	-		PR69B	3	
AB2	NC	-		PR69A	3	
AA5	NC	-		PR68B	3	
Y5	NC	-		PR68A	3	
AD1	NC	-		PR67B	3	
AC1	NC	-		PR67A	3	
AB1	NC	-		PR64B	3	
AA1	NC	-		PR64A	3	
Y3	NC	-		PR61B	3	
W3	NC	-		PR61A	3	
Y1	NC	-		PR59B	3	
W1	NC	-		PR59A	3	
R5	NC	-		PR41D	2	
P5	NC	-		PR41C	2	
K1	NC	-		PR41B	2	
J1	NC	-		PR41A	2	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AN15	PB89A	4	PCLKT4_2
AN14	PB89B	4	PCLKC4_2
AE16	PB89C	4	PCLKT4_7
AD16	PB89D	4	PCLKC4_7
AK15	PB90A	4	PCLKT4_1
AK14	PB90B	4	PCLKC4_1
AG15	PB90C	4	PCLKT4_6
AG14	PB90D	4	PCLKC4_6
AM13	PB91A	4	PCLKT4_0
AM12	PB91B	4	PCLKC4_0
AJ12	PB91C	4	VREF2_4
AJ11	PB91D	4	
AL13	PB93A	4	PCLKT4_5
AL12	PB93B	4	PCLKC4_5
AH12	PB93C	4	
AH11	PB93D	4	
AN13	PB94A	4	PCLKT4_3
AN12	PB94B	4	PCLKC4_3
AD14	PB94C	4	PCLKT4_4
AD15	PB94D	4	PCLKC4_4
AP13	PB87A	4	
AP12	PB87B	4	
AK13	PB87C	4	
AK12	PB87D	4	
AP11	PB97A	4	
AP10	PB97B	4	
AN11	PB113A	4	
AN10	PB113B	4	
AF14	PB113C	4	
AF13	PB113D	4	
AM10	PB115A	4	
AM9	PB115B	4	
AE14	PB115C	4	
AE13	PB115D	4	
AP9	PB118A	4	
AP8	PB118B	4	
AK11	PB118C	4	
AK10	PB118D	4	
AL10	PB121A	4	
AL9	PB121B	4	
AF12	PB121C	4	
AF11	PB121D	4	
AN9	PB123A	4	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
AL4	PR117B	3	LRC_DLLC_IN_F/LRC_DLLC_FB_E
AL3	PR117A	3	LRC_DLLT_IN_F/LRC_DLLT_FB_E
AD10	PR116D	3	
AD9	PR116C	3	
AH4	PR116B	3	
AJ4	PR116A	3	
AK5	PR115D	3	LRC_DLLC_IN_E/LRC_DLLC_FB_F
AJ5	PR115C	3	LRC_DLLT_IN_E/LRC_DLLT_FB_F
AM1	PR115B	3	
AL1	PR115A	3	
AH5	PR112D	3	
AG5	PR112C	3	
AL2	PR112B	3	
AK2	PR112A	3	
AB9	PR109D	3	
AC9	PR109C	3	
AH1	PR109B	3	
AG1	PR109A	3	
AE8	PR107D	3	VREF2_3
AD8	PR107C	3	
AJ3	PR107B	3	
AH3	PR107A	3	
AD7	PR104D	3	
AC7	PR104C	3	
AJ2	PR104B	3	
AH2	PR104A	3	
AF6	PR103D	3	
AF5	PR103C	3	
AF4	PR103B	3	
AE4	PR103A	3	
AD6	PR99D	3	
AC6	PR99C	3	
AG2	PR99B	3	
AF2	PR99A	3	
AC8	PR98D	3	
AB8	PR98C	3	
AK1	PR98B	3	
AJ1	PR98A	3	
AB10	PR96D	3	
AA10	PR96C	3	
AF3	PR96B	3	
AE3	PR96A	3	
AE5	PR94D	3	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
V8	PR65D	3	PCLKC3_3
U8	PR65C	3	PCLKT3_3
U5	PR65B	3	
T5	PR65A	3	
V6	PR64D	3	PCLKC3_1
U6	PR64C	3	PCLKT3_1
T4	PR64B	3	PCLKC3_0
T3	PR64A	3	PCLKT3_0
U9	PR62D	2	PCLKC2_2
T9	PR62C	2	PCLKT2_2
R2	PR62B	2	PCLKC2_0
P2	PR62A	2	PCLKT2_0
T11	PR61D	2	PCLKC2_3
U11	PR61C	2	PCLKT2_3
R4	PR61B	2	PCLKC2_1
R3	PR61A	2	PCLKT2_1
T8	PR60D	2	
R8	PR60C	2	
P1	PR60B	2	
N1	PR60A	2	
R6	PR57D	2	
P6	PR57C	2	
M1	PR57B	2	
L1	PR57A	2	
T10	PR56D	2	
U10	PR56C	2	
N2	PR56B	2	
M2	PR56A	2	
R11	PR51D	2	
P11	PR51C	2	
N4	PR51B	2	
M4	PR51A	2	
N5	PR49D	2	
M5	PR49C	2	
L2	PR49B	2	
K2	PR49A	2	
P8	PR47D	2	
N8	PR47C	2	
J2	PR47B	2	
H2	PR47A	2	
M6	PR45D	2	
L6	PR45C	2	
K3	PR45B	2	

LFSC/M115 Logic Signal Connections: 1152 fcBGA[1, 2]

Ball Number	LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function
J3	PR45A	2	
M8	PR43D	2	DIFFR_2
L8	PR43C	2	VREF1_2
K4	PR43B	2	
J4	PR43A	2	
M7	PR26D	2	
L7	PR26C	2	
J5	PR26B	2	
H5	PR26A	2	
N9	PR19D	2	
P9	PR19C	2	
G3	PR19B	2	
F3	PR19A	2	
J6	PR18D	2	VREF2_2
H6	PR18C	2	
E2	PR18B	2	URC_DLLC_IN_D/URC_DLLC_FB_C
D2	PR18A	2	URC_DLLT_IN_D/URC_DLLT_FB_C
P10	PR17D	2	URC_PLLC_IN_B/URC_PLLC_FB_A
N10	PR17C	2	URC_PLLT_IN_B/URC_PLLT_FB_A
G4	PR17B	2	URC_DLLC_IN_C/URC_DLLC_FB_D
F4	PR17A	2	URC_DLLT_IN_C/URC_DLLT_FB_D
J7	PR15D	2	
H7	PR15C	2	
G5	PR15B	2	URC_PLLC_IN_A/URC_PLLC_FB_B
F5	PR15A	2	URC_PLLT_IN_A/URC_PLLT_FB_B
C2	VCCJ	-	
M9	TDO	-	TDO
L9	TMS	-	
D1	TCK	-	
C1	TDI	-	
J8	PROGRAMN	1	
K8	MPIIRQN	1	CFGIRQN/MPI_IRQ_N
B2	CCLK	1	
H9	RESP_URC	-	
H10	VCC12	-	
H8	A_REFCLKN_R	-	
G8	A_REFCLKP_R	-	
C3	VCC12	-	
D3	A_VDDIB0_R	-	
A3	A_HDINP0_R	-	PCS 3E0 CH 0 IN P
B3	A_HDINN0_R	-	PCS 3E0 CH 0 IN N
E5	VCC12	-	
A4	A_HDOUTP0_R	-	PCS 3E0 CH 0 OUT P

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AP1	PR90B	3		PR109B	3	
AN1	PR90A	3		PR109A	3	
AK10	PR89D	3	VREF2_3	PR107D	3	VREF2_3
AJ10	PR89C	3		PR107C	3	
AM5	PR89B	3		PR107B	3	
AL5	PR89A	3		PR107A	3	
AL7	PR86D	3		PR104D	3	
AK7	PR86C	3		PR104C	3	
AM1	PR86B	3		PR104B	3	
AL1	PR86A	3		PR104A	3	
AJ11	PR85D	3		PR103D	3	
AH11	PR85C	3		PR103C	3	
AK5	PR85B	3		PR103B	3	
AJ5	PR85A	3		PR103A	3	
AK9	PR84D	3		PR99D	3	
AJ9	PR84C	3		PR99C	3	
AK3	PR84B	3		PR99B	3	
AJ3	PR84A	3		PR99A	3	
AK6	PR82D	3		PR98D	3	
AJ6	PR82C	3		PR98C	3	
AK2	PR82B	3		PR98B	3	
AJ2	PR82A	3		PR98A	3	
AH10	PR81D	3		PR96D	3	
AG10	PR81C	3		PR96C	3	
AK1	PR81B	3		PR96B	3	
AJ1	PR81A	3		PR96A	3	
AH9	PR80D	3		PR94D	3	
AG9	PR80C	3		PR94C	3	
AH2	PR80B	3		PR94B	3	
AG2	PR80A	3		PR94A	3	
AH8	PR78D	3		PR92D	3	
AG8	PR78C	3		PR92C	3	
AG1	PR78B	3		PR92B	3	
AH1	PR78A	3		PR92A	3	
AG14	PR77D	3		PR91D	3	
AF14	PR77C	3		PR91C	3	
AG4	PR77B	3		PR91B	3	
AF4	PR77A	3		PR91A	3	
AH7	PR76D	3	DIFFR_3	PR90D	3	DIFFR_3
AG7	PR76C	3		PR90C	3	
AG3	PR76B	3		PR90B	3	
AF3	PR76A	3		PR90A	3	
AH6	PR74D	3		PR88D	3	
AG6	PR74C	3		PR88C	3	
AF1	PR74B	3		PR88B	3	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AG38	NC	-		PL95A	6	
AH38	NC	-		PL95B	6	
AJ39	NC	-		PL100A	6	
AK39	NC	-		PL100B	6	
AL41	NC	-		PL105A	6	
AM41	NC	-		PL105B	6	
AN40	NC	-		PL108A	6	
AM40	NC	-		PL108B	6	
AM39	NC	-		PL111A	6	
AN39	NC	-		PL111B	6	
AR42	NC	-		PL113A	6	
AT42	NC	-		PL113B	6	
AT1	NC	-		PR113B	3	
AR1	NC	-		PR113A	3	
AN4	NC	-		PR111B	3	
AM4	NC	-		PR111A	3	
AM3	NC	-		PR108B	3	
AN3	NC	-		PR108A	3	
AM2	NC	-		PR105B	3	
AL2	NC	-		PR105A	3	
AK4	NC	-		PR100B	3	
AJ4	NC	-		PR100A	3	
AH5	NC	-		PR95B	3	
AG5	NC	-		PR95A	3	
P6	NC	-		PR39B	2	
N6	NC	-		PR39A	2	
L3	NC	-		PR36B	2	
K3	NC	-		PR36A	2	
M5	NC	-		PR35A	2	
L4	NC	-		PR32B	2	
K4	NC	-		PR32A	2	
A2	GND	-		GND	-	
A41	GND	-		GND	-	
AA20	GND	-		GND	-	
AA23	GND	-		GND	-	
AA3	GND	-		GND	-	
AA39	GND	-		GND	-	
AB20	GND	-		GND	-	
AB23	GND	-		GND	-	
AB4	GND	-		GND	-	
AB40	GND	-		GND	-	
AC17	GND	-		GND	-	
AC19	GND	-		GND	-	
AC21	GND	-		GND	-	
AC22	GND	-		GND	-	

LFSC/M80, LFSC/M115 Logic Signal Connections: 1704 fcBGA[1, 2] (Cont.)

Ball Number	LFSC/M80			LFSC/M115		
	Ball Function	VCCIO Bank	Dual Function	Ball Function	VCCIO Bank	Dual Function
AH27	VCCAUX	-		VCCAUX	-	
AH29	VCCAUX	-		VCCAUX	-	
AJ14	VCCAUX	-		VCCAUX	-	
AJ15	VCCAUX	-		VCCAUX	-	
AJ28	VCCAUX	-		VCCAUX	-	
AJ29	VCCAUX	-		VCCAUX	-	
P14	VCCAUX	-		VCCAUX	-	
P15	VCCAUX	-		VCCAUX	-	
P28	VCCAUX	-		VCCAUX	-	
P29	VCCAUX	-		VCCAUX	-	
R14	VCCAUX	-		VCCAUX	-	
R16	VCCAUX	-		VCCAUX	-	
R17	VCCAUX	-		VCCAUX	-	
R18	VCCAUX	-		VCCAUX	-	
R19	VCCAUX	-		VCCAUX	-	
R20	VCCAUX	-		VCCAUX	-	
R23	VCCAUX	-		VCCAUX	-	
R24	VCCAUX	-		VCCAUX	-	
R25	VCCAUX	-		VCCAUX	-	
R26	VCCAUX	-		VCCAUX	-	
R27	VCCAUX	-		VCCAUX	-	
R29	VCCAUX	-		VCCAUX	-	
T15	VCCAUX	-		VCCAUX	-	
T28	VCCAUX	-		VCCAUX	-	
U15	VCCAUX	-		VCCAUX	-	
U28	VCCAUX	-		VCCAUX	-	
V15	VCCAUX	-		VCCAUX	-	
V28	VCCAUX	-		VCCAUX	-	
W15	VCCAUX	-		VCCAUX	-	
W28	VCCAUX	-		VCCAUX	-	
Y15	VCCAUX	-		VCCAUX	-	
Y28	VCCAUX	-		VCCAUX	-	
F3	VCCIO1	-		VCCIO1	-	
F39	VCCIO1	-		VCCIO1	-	
G35	VCCIO1	-		VCCIO1	-	
G8	VCCIO1	-		VCCIO1	-	
L19	VCCIO1	-		VCCIO1	-	
L24	VCCIO1	-		VCCIO1	-	
M16	VCCIO1	-		VCCIO1	-	
M27	VCCIO1	-		VCCIO1	-	
N11	VCCIO1	-		VCCIO1	-	
N32	VCCIO1	-		VCCIO1	-	
AA4	VCCIO2	-		VCCIO2	-	
H7	VCCIO2	-		VCCIO2	-	
J4	VCCIO2	-		VCCIO2	-	

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FC1152C[1]	-6	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FC1152C[1]	-5	Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FF1152C	-6	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FF1152C	-5	Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FC1704C[1]	-6	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FC1704C[1]	-5	Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FF1704C	-6	Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FF1704C	-5	Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

Commercial, Cont.

Part Number	Grade	Package	Balls	Temp.	LUTs (K)
LFSCM3GA115EP1-6FCN1152C[1]	-6	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FCN1152C[1]	-5	Lead-Free Ceramic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FFN1152C	-6	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-5FFN1152C	-5	Lead-Free Organic fcBGA	1152	COM	115.2
LFSCM3GA115EP1-6FCN1704C[1]	-6	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FCN1704C[1]	-5	Lead-Free Ceramic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-6FFN1704C	-6	Lead-Free Organic fcBGA	1704	COM	115.2
LFSCM3GA115EP1-5FFN1704C	-5	Lead-Free Organic fcBGA	1704	COM	115.2

1. Converted to organic flip-chip BGA package per PCN #01A-10.

LatticeSC/M Family Data Sheet Supplemental Information

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For Further Information

For further information about the flexiPCS, see the LatticeSC/M Family flexiPCS Data Sheet.

A variety of technical notes for the LatticeSC/M family are also available on the Lattice Semiconductor website at www.latticesemi.com.

- LatticeSC PURESPEED I/O Usage Guide (TN1088)
- LatticeSC PURESPEED I/O Adaptive Input Logic User's Guide (TN1158)
- LatticeSC sysCLOCK PLL/DLL User's Guide (TN1098)
- On-Chip Memory Usage Guide for LatticeSC Devices (TN1094)
- LatticeSC/M DDR/DDR2 SDRAM Memory Interface User's Guide (TN1099)
- LatticeSC QDRII/II+ SRAM Memory Interface User's Guide (TN1096)
- LatticeSC sysCONFIG Usage Guide (TN1080)
- LatticeSC MPI/System Bus (TN1085)
- SPI Serial Flash Programming Using ispJTAG in LatticeSC Devices (TN1100)
- Power Estimation and Management for LatticeSC Devices (TN1101)
- LatticeSC SERDES Jitter (TN1084)
- LatticeSC FPGAs: Implementing 3.3V Interfaces in 2.5V VCCIO Banks (TN1110)
- Lattice PCI Express Basic Demo User's Guide (UG08)
- LatticeSC flexiPCS/SERDES Design Guide (TN1145)
- Temperature Sensing Diode in LatticeSC Devices (TN1115)
- SPI4.2 Interoperability Between ORSPI4 and LatticeSC Devices (TN1116)

For further information on Interface standards refer to the following websites:

- JEDEC Standards (LVTTL, LVCMOS, SSTL, HSTL): www.jedec.org
- Optical Interface (SPI-4.2, XSBI, CSIX and XGMII): www.oiforum.com
- RAPIDIO: www.rapidio.org
- PCI/PCIX: ww.pcisig.com

Date	Version	Section	Change Summary
August 2006 (cont.)	01.3 (cont.)	DC and Switching Characteristics (cont.)	Updated LatticeSC Family Timing Adders with ispLEVER 6.0 SP1 results
			Updated PLL Timing Parameters based on PDE testing results
			Removed RDDATA parameter from sysCONFIG readback timing table
		Multiple	Changed TDO/RDDATA to TDO
		Pinout Information	Removed all MPI signals from SC15 256 pin package Dual Function Column
			Added note to SC15, SC25 900 pin package that the package supports a 16 bit MPI
			Added note that pin D3 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note that pin D28 in an SC15 and SC25 900 pin package should not be used for single-ended outputs
			Added note to SC25 1020 pin package that the package supports a 16 bit MPI
			Added note to SC80 1152 pin package that the package supports a 32 bit MPI
			Added note to SC80 1704 pin package that the package supports a 32 bit MPI
		Ordering Information	Changed “fcBGA” for the 1020 packages to “ffBGA”
November 2006	01.4	Introduction	LatticeSC Family Selection Guide table – I/O count for SC80 device, 1704 fcBGA package changed to 904/32. I/O count for SC115 device, 1704 fcBGA package changed to 942/32.
		DC and Switching Characteristics	DC Electrical Characteristics table – Updated the initialization and standby supply current values.
			DC Electrical Characteristics table – Updated the sysCONFIG Master Parallel mode RCLK low and RCLK high time specifications.
			DC Electrical Characteristics table – Updated VCCIO values for LVPECL33 I/Os.
		Pin Information	Pin Information Summary table - Changed number of single ended user I/Os from 906 to 904 for 1704 fcBGA.
			Removed the single-ended only output restriction on pins D3 and D28 in an SC15 and SC25 900 pin package.
		Ordering Information	Ordering Information tables - Changed number of I/Os from 906 to 904 for 1704 fcBGA.
			Added ordering part numbers for LatticeSC/SCM 40K and 115K LUT devices.
			Added lead-free ordering part numbers.
		Multiple	Changed number of available SC80 I/O from 906 to 904.
			Changed number of available SC115 I/O from 944 to 942.
January 2007	01.4a	Architecture	Added EBR Asynchronous Reset section.
February 2007	01.4b	Architecture	Updated EBR Asynchronous Reset section.
March 2007	01.5	Architecture	Added EBR asynchronous reset clarification
			Clarified that differential drivers are not supported in banks 1, 4 and 5
		DC and Switching Characteristics	Added clarification for the description of the junction temperature specification in the Absolute Maximum Ratings section.
			Updated Initialization and Standby Current table.
			Updated LatticeSC External Switching Characteristics with ispLEVER 6.1 SP1 results.